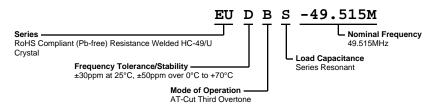
EUDBS-49.515M





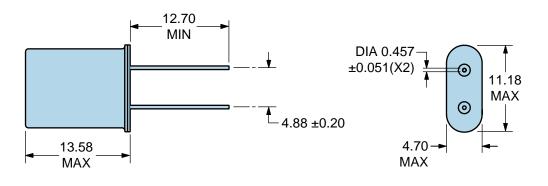




ELECTRICAL SPECIFICATIONS		
Nominal Frequency	49.515MHz	
Frequency Tolerance/Stability	±30ppm at 25°C, ±50ppm over 0°C to +70°C	
Aging at 25°C	±5ppm/year Maximum	
Load Capacitance	Series Resonant	
Shunt Capacitance (C0)	7pF Maximum	
Equivalent Series Resistance	40 Ohms Maximum	
Mode of Operation	AT-Cut Third Overtone	
Drive Level	2mWatts Maximum	
Storage Temperature Range	-40°C to +125°C	
Insulation Resistance	500 Megaohms Minimum at 100Vdc	

ENVIRONMENTAL & MECHANICAL SPECIFICATIONS		
Fine Leak Test	MIL-STD-883, Method 1014, Condition A	
Gross Leak Test	MIL-STD-883, Method 1014, Condition C	
Lead Integrity	MIL-STD-883, Method 2004	
Lead Termination	Sn 2µm - 6µm	
Mechanical Shock	MIL-STD-202, Method 213, Condition C	
Resistance to Soldering Heat	MIL-STD-202, Method 210	
Resistance to Solvents	MIL-STD-202, Method 215	
Solderability	MIL-STD-883, Method 2003	
Temperature Cycling	MIL-STD-883, Method 1010	
Vibration	MIL-STD-883, Method 2007, Condition A	

MECHANICAL DIMENSIONS (all dimensions in millimeters)



LINE	MARKING
1	ECLIPTEK
2	E49.515M <i>E</i> =Configuration Designator
3	XX XX=Ecliptek Manufacturing Code

EUDBS-49.515M



Recommended Solder Reflow Methods



High Temperature Solder Bath (Wave Solder)

<u> </u>	, , , , , , , , , , , , , , , , , , ,
T _s MAX to T _L (Ramp-up Rate)	3°C/second Maximum
Preheat	
- Temperature Minimum (T _s MIN)	150°C
- Temperature Typical (T _s TYP)	175°C
- Temperature Maximum (T _s MAX)	200°C
- Time (t _s MIN)	60 - 180 Seconds
Ramp-up Rate (T _L to T _P)	3°C/second Maximum
Time Maintained Above:	
- Temperature (T _L)	217°C
- Time (t∟)	60 - 150 Seconds
Peak Temperature (T _P)	260°C Maximum for 10 Seconds Maximum
Target Peak Temperature (T _P Target)	250°C +0/-5°C
Time within 5°C of actual peak (tp)	20 - 40 seconds
Ramp-down Rate	6°C/second Maximum
Time 25°C to Peak Temperature (t)	8 minutes Maximum
Moisture Sensitivity Level	Level 1

EUDBS-49.515M



Recommended Solder Reflow Methods



Low Temperature Solder Bath (Wave Solder)

T _S MAX to T _L (Ramp-up Rate)	5°C/second Maximum
Preheat	
- Temperature Minimum (T _s MIN)	N/A
- Temperature Typical (T _S TYP)	150°C
- Temperature Maximum (T _s MAX)	N/A
- Time (t _s MIN)	30 - 60 Seconds
Ramp-up Rate (T _L to T _P)	5°C/second Maximum
Time Maintained Above:	
- Temperature (T∟)	150°C
- Time (t∟)	200 Seconds Maximum
Peak Temperature (T _P)	245°C Maximum
Target Peak Temperature (T _P Target)	245°C Maximum 1 Time / 235°C Maximum 2 Times
Time within 5°C of actual peak (tp)	5 seconds Maximum 1 Time / 15 seconds Maximum 2 Times
Ramp-down Rate	5°C/second Maximum
Time 25°C to Peak Temperature (t)	N/A
Moisture Sensitivity Level	Level 1

Low Temperature Manual Soldering

185°C Maximum for 10 seconds Maximum, 2 times Maximum.

High Temperature Manual Soldering

260°C Maximum for 5 seconds Maximum, 2 times Maximum.